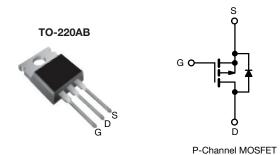
Vishay Siliconix

Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	-60	-60			
R _{DS(on)} (Ω)	V _{GS} = -10 V	0.50			
Q _g max. (nC)	12				
Q _{gs} (nC)	3.8	3.8			
Q _{gd} (nC)	5.1	5.1			
Configuration	Sing	Single			

FEATURES

- · Dynamic dV/dt rating
- · Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF9Z14PbF		
Lead (Pb)-free and halogen-free	IRF9Z14PbF-BE3		

ABSOLUTE MAXIMUM RATINGS (T_C	= 25 °C, uni	ess otherwis	se notea)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	-60	V	
Gate-source voltage			V_{GS}	± 20		
Continuous drain current	V _{GS} at 10 V	T _C = 25 °C	- I _D	-6.7		
	VGS at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		-4.7	Α	
Pulsed drain current ^a			I _{DM}	-27	1	
Linear derating factor				0.29	W/°C	
Single pulse avalanche energy b			E _{AS}	140	mJ	
Repetitive avalanche current a			I _{AR}	-6.7	А	
Repetitive avalanche energy ^a			E _{AR}	4.3	mJ	
Maximum power dissipation	$T_C = 1$	25 °C	P_{D}	43	W	
Peak diode recovery dV/dt ^c			dV/dt	-4.5	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) ^d	For 10 s			300	7	
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
			Ī	1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = -25 V, starting T_J = 25 °C, L = 3.6 mH, R_g = 25 Ω , I_{AS} = -6.7 A (see fig. 12)
- c. $I_{SD} \le$ -6.7 A, $dI/dt \le$ 90 A/µs, $V_{DD} \le V_{DS}$, $T_J \le$ 175 °C
- d. 1.6 mm from case



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	3.5		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-60	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = -1 mA		-0.060	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$		-2.0	-	-4.0	V
Gate-source leakage	I _{GSS}	V	V _{GS} = ± 20 V		-	± 100	nA
Zava sata valtasa duain avuvant	1	V _{DS} = -60 V, V _{GS} = 0 V		-	-	-100	μА
Zero gate voltage drain current	I _{DSS}	$V_{DS} = -48 \text{ V},$	V _{DS} = -48 V, V _{GS} = 0 V, T _J = 150 °C		-	-500	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = -10 V	I _D = -4.0 A ^b	-	-	0.50	Ω
Forward transconductance	9 _{fs}	V _{DS} = -25 V, I _D = -4.0 A ^b		1.4	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = -25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$		-	270	-	pF
Output capacitance	C _{oss}				170	-	
Reverse transfer capacitance	C _{rss}			-	31	-	
Total gate charge	Qg			-	-	12	nC
Gate-source charge	Q _{gs}	$V_{GS} = -10 \text{ V}$	$I_D = -6.7 \text{ A}, V_{DS} = -48 \text{ V},$ see fig. 6 and 13 b	-	-	3.8	
Gate-drain charge	Q _{gd}		see lig. 6 and 13	=	-	5.1	
Turn-on delay time	t _{d(on)}	$V_{DD} = -30 \text{ V, } I_D = -6.7 \text{ A,}$ $R_g = 24 \ \Omega, \ R_D = 4.0 \ \Omega, \ \text{see fig. 10}^{\text{ b}}$		-	11	-	- ns
Rise time	t _r			-	63	-	
Turn-off delay time	t _{d(off)}			-	10	-	
Fall time	t _f			-	31	-	
Gate input resistance	Rg	f = 1 MHz, open drain		1.4	-	8.7	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	_	- nH
Internal source inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristic	es						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	-6.7	A
Pulsed diode forward current ^a	I _{SM}			-	-	-27	
Body diode voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = -6.7 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	-5.5	V
Body diode reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = -6.7 \text{ A, dl/dt} = 100 \text{ A/}\mu\text{s}^{\text{b}}$		-	80	160	ns
Body diode reverse recovery charge	Q _{rr}			-	0.096	0.19	μC
Forward turn-on time	t _{on}	Intrinsic turr	n-on time is negligible (tur	n-on is do	minated b	v L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

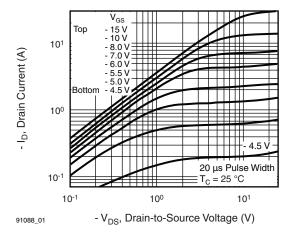


Fig. 1 - Typical Output Characteristics, $T_C = 25$ °C

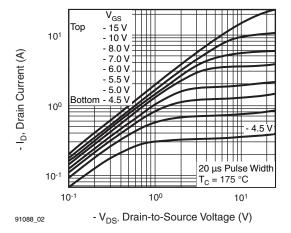


Fig. 2 - Typical Output Characteristics, T_C = 175 $^{\circ}$ C

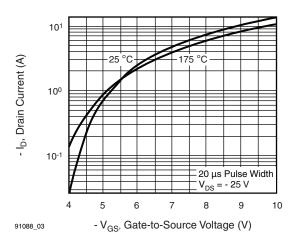


Fig. 3 - Typical Transfer Characteristics

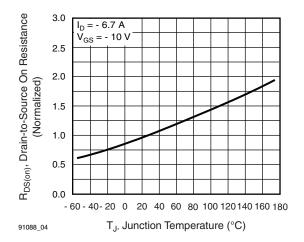


Fig. 4 - Normalized On-Resistance vs. Temperature

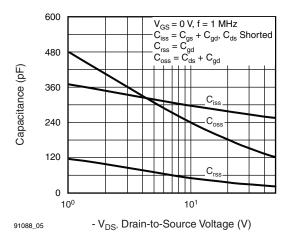


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

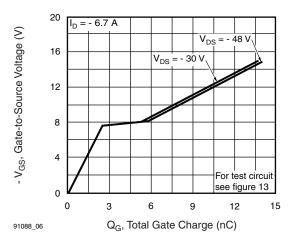


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



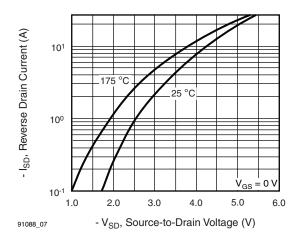


Fig. 7 - Typical Source-Drain Diode Forward Voltage

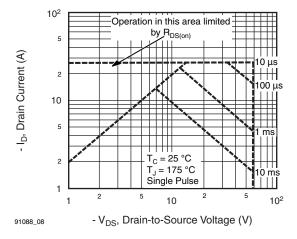


Fig. 8 - Maximum Safe Operating Area

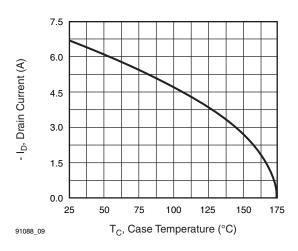


Fig. 9 - Maximum Drain Current vs. Case Temperature

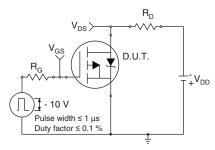


Fig. 10a - Switching Time Test Circuit

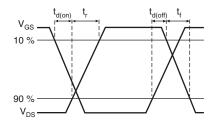


Fig. 10b - Switching Time Waveforms

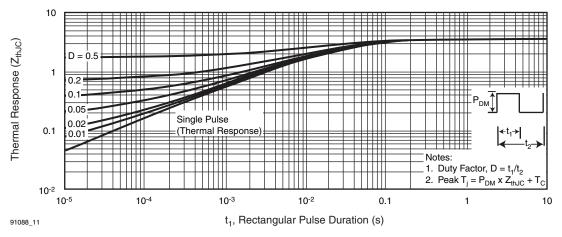


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



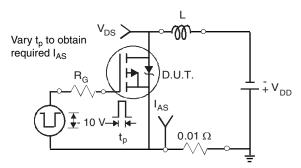


Fig. 12a - Unclamped Inductive Test Circuit

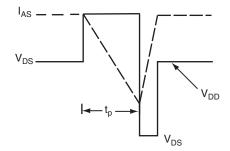


Fig. 12b - Unclamped Inductive Waveforms

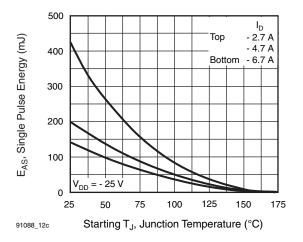


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

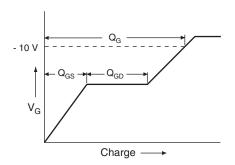


Fig. 13a - Basic Gate Charge Waveform

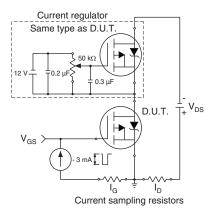
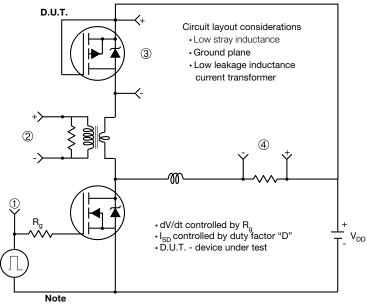


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



· Compliment N-Channel of D.U.T. for driver

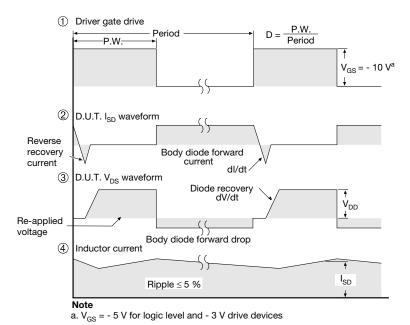


Fig. 14 - For P-Channel

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